/ Descriptions

P

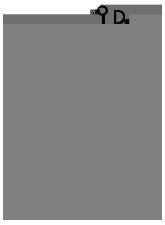
/ Features

±

。HF Product.

/ Applications

/ Equivalent Circuit



/ Pinning

/ Marking

/ Electrical Characteristic Curve

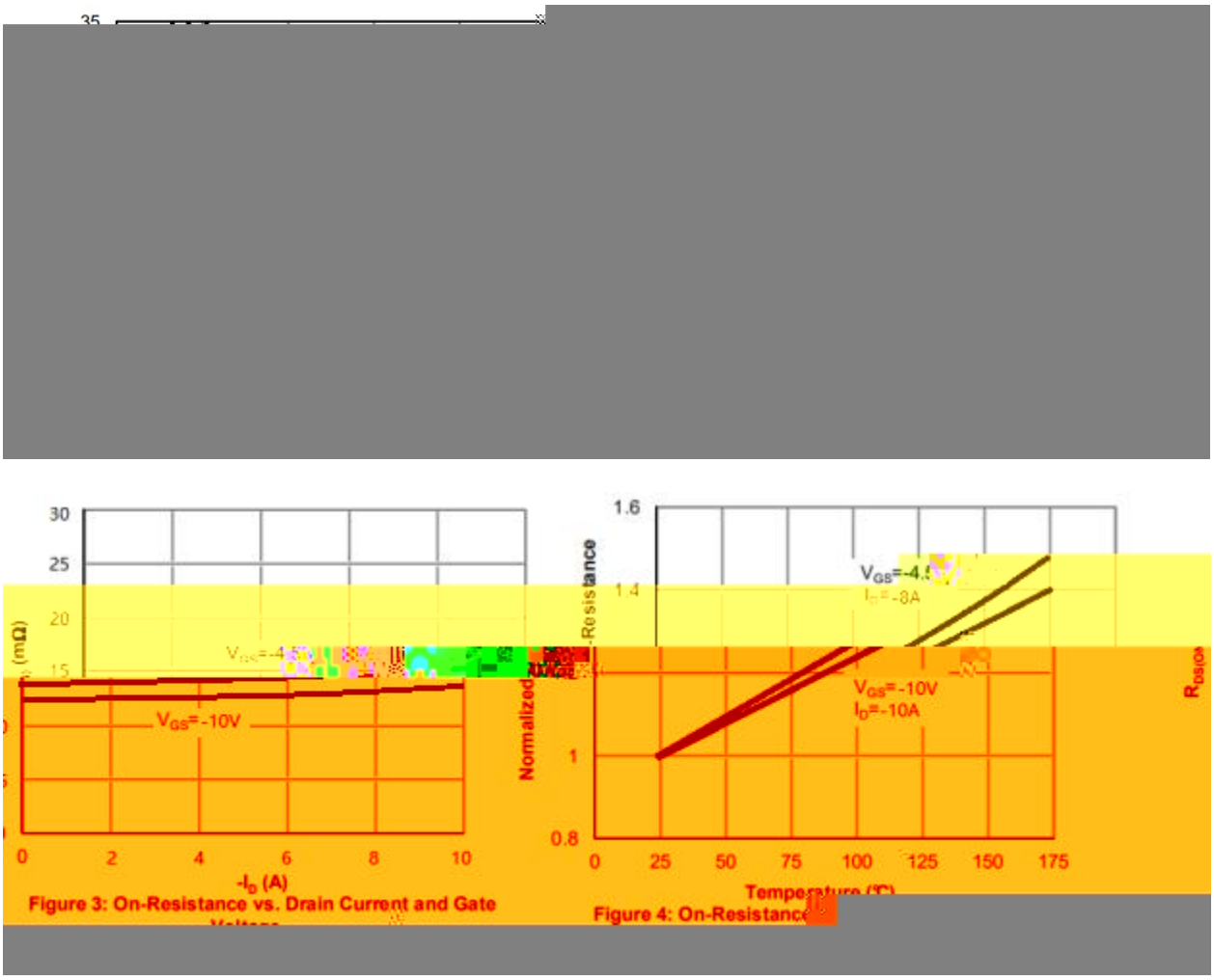
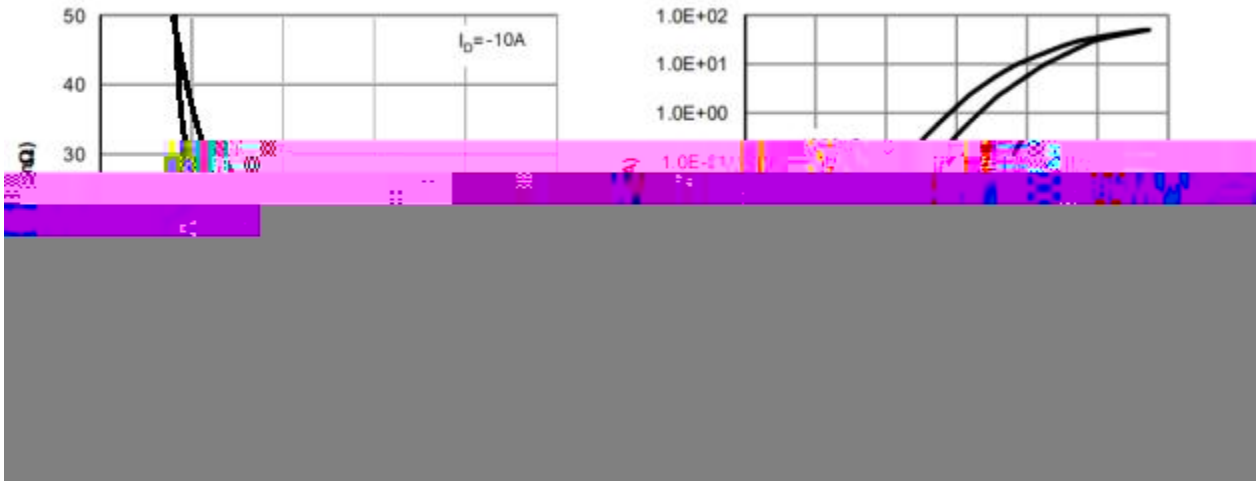
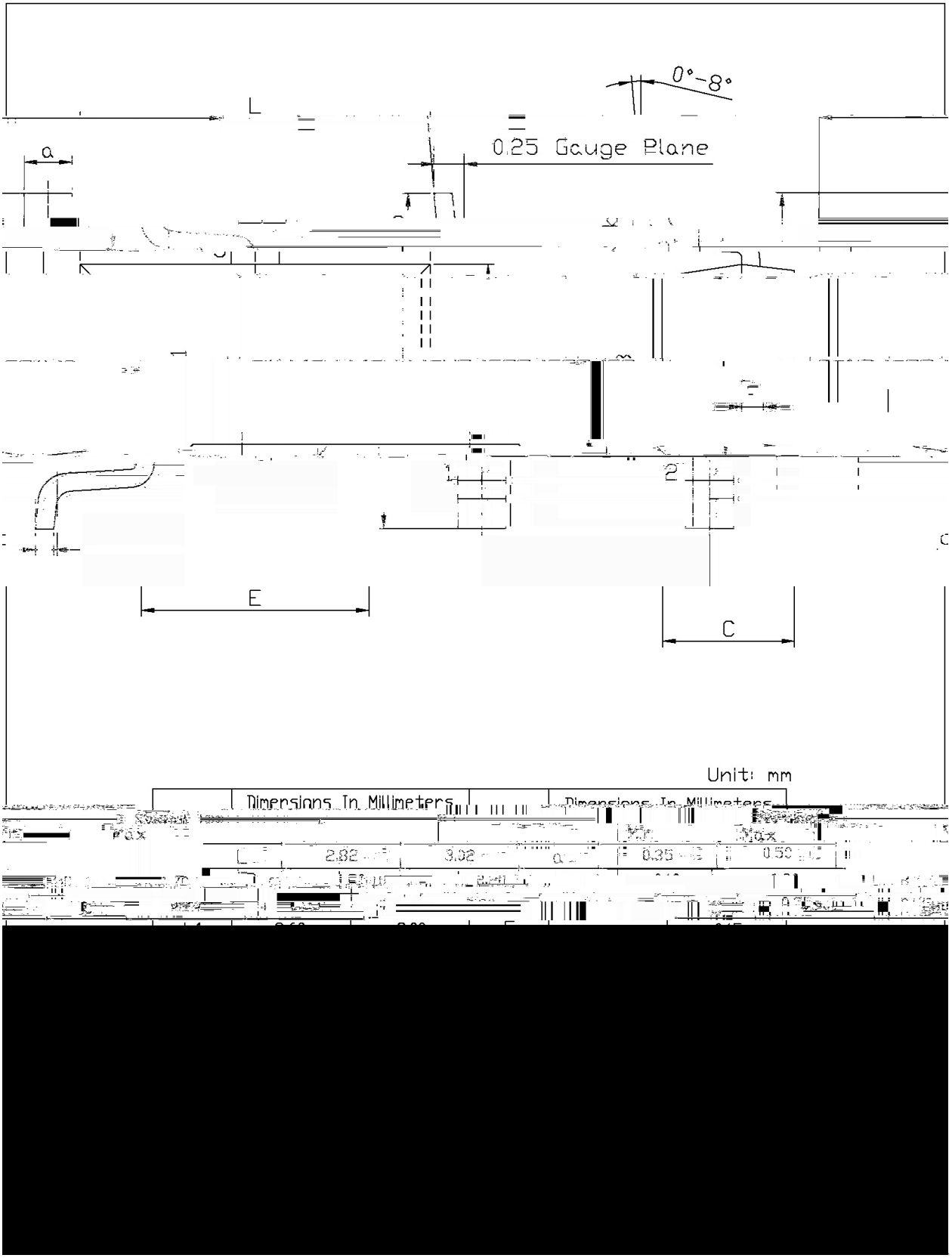


Figure 3: On-Resistance vs. Drain Current and Gate

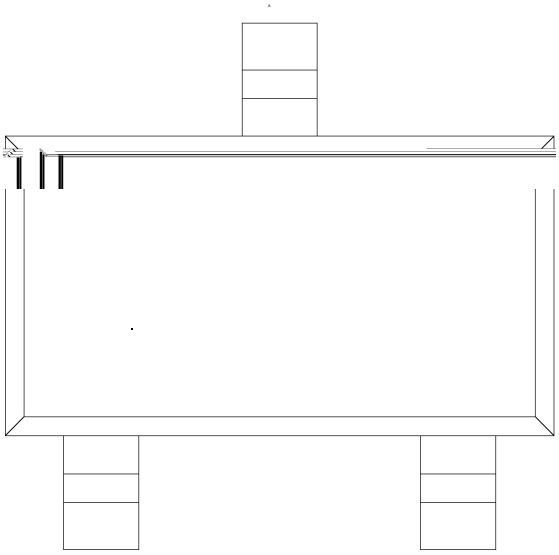
Figure 4: On-Resistance



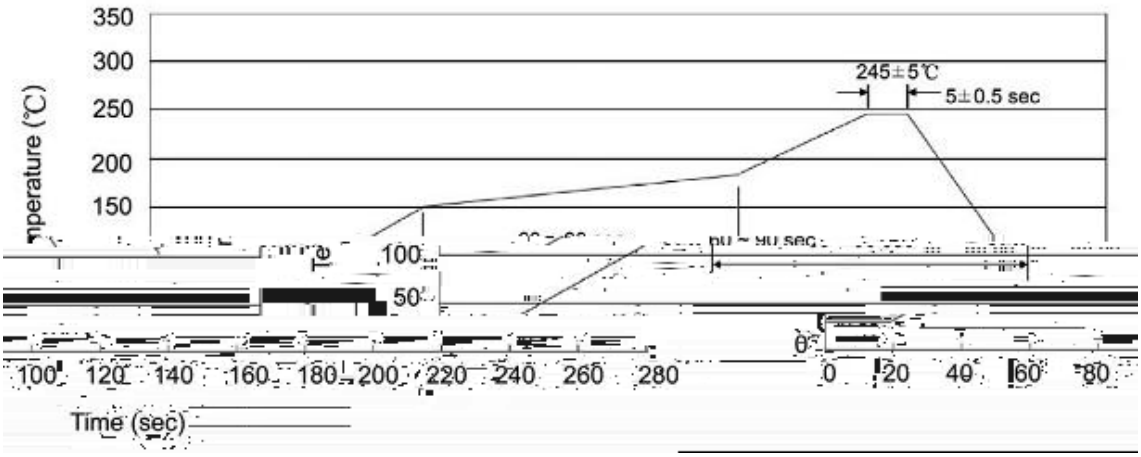
/ Package Dimensions



/ Marking Instructions



( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

/ Resistance to Soldering Heat Test Conditions

± ± ± ±

/ Packaging SPEC.

封装形式	包装数量					包装尺寸 :		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT23-3	3,000	10	30,000	4	120,000	7″ ×8	210×205×205	445×230×435

/ Notices